Early Warning System

EIB-20240024 NXP EUROPEAN SEMICONDUCTOR RDI



Quick Facts

Countries	Austria, France, Germany, Netherlands, Romania			
Financial Institutions	European Investment Bank (EIB)			
Status	Approved			
Bank Risk Rating	U			
Voting Date	2024-11-22			
Borrower	NXP BV			
Sectors	Industry and Trade			
Investment Type(s)	Loan			
Investment Amount (USD)	\$ 1,041.83 million			
Project Cost (USD)	\$ 2,194.09 million			

Project Description

According to the Bank's website, the project will support the promoter's research, development and innovation (RDI) investments in a wide range of semiconductor products in the area of Automotive, IoT, Mobile, and Communication Infrastructure. RDI investments will focus in particular on microcontrollers, application processors, communication processors, connectivity chipsets, analogue and interface devices, RF power amplifiers, security controllers and sensors.

The aim is to develop next generation of semiconductor devices and solutions. RDI investments will contribute to build stateof-the-art European chip ecosystem and will involve investment in five EU countries.

Early Warning System Project Analysis

Semiconductor RDI activities are not specifically covered by Annexes I & II of the environmental impact assessment (EIA) Directive 2011/92/EC (as amended by EIA Directive 2014/52/EU).

Investment Description

• European Investment Bank (EIB)

Private Actors Description

NXP B.V. develops and sells semiconductor devices. The Company offers amplifiers, bipolar transistors, data converters, diodes, micro controllers, power management integrated circuits, thyristors, applications processors, instrument clusters, advanced driver assistance systems, autonomous driving, and other related products. NXP serves customers worldwide.





Private Actor 1	Private Actor 1 Role	Private Actor 1 Sector	Relation	Private Actor 2	Private Actor 2 Role	Private Actor 2 Sector
-	-	-	-	NXP B.V.	Client	-

Contact Information

No contacts available at the time of disclosure.

ACCESS TO INFORMATION

You can submit an information request for project information at: https://www.eib.org/en/infocentre/registers/request-form/request-form-default.htm

ACCOUNTABILITY MECHANISM OF EIB

The EIB Complaints Mechanism is designed to facilitate and handle complaints against the EIB by individuals, organizations or corporations affected by EIB activities. When exercising the right to lodge a complaint against the EIB, any member of the public has access to a two-tier procedure, one internal - the Complaints Mechanism Office - and one external - the European Ombudsman. A complaint can be lodged via a written communication addressed to the Secretary General of the EIB, via email to the dedicated email address: complaints@eib.org, by completing the online complaint form available at the following address: http://www.eib.org/complaints/form via fax or delivered directly to the EIB Complaints Mechanism Division, any EIB local representation office or any EIB staff. For further details, check:

http://www.eib.org/attachments/strategies/complaints mechanism policy en.pdf

When dissatisfied with a complaint to the EIB Complaints Mechanism, citizens can then turn towards the European Ombudsman. A memorandum of Understanding has been signed between the EIB and the European Ombudsman establishes that citizens (even outside of the EU if the Ombudsman finds their complaint justified) can turn towards the Ombudsman on issues related to 'maladministration' by the EIB. Note that before going to the Ombudsman, an attempt must be made to resolve the case by contacting the EIB. In addition, the complaint must be made within two years of the date when the facts on which your complaint is based became known to you. You can write to the Ombudsman in any of the languages of the European Union. Additional details, including filing requirements and complaint forms, are available at: http://www.ombudsman.europa.eu/atyourservice/interactiveguide.faces

Bank Documents

• Environmental and Social Data Sheet (ESDS) - NXP EUROPEAN SEMICONDUCTOR RDI